12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20180830000
Datasheet for THS3491
Information Only

Date: August 31, 2018
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
THS3491IDDAT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180830000	PCN Date:	August 31, 2018
Title:	Datasheet for THS3491		
Customer Contact:	PCN Manager	Dept:	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

TEXAS INSTRUMENTS

THS3491

SBOS875B – AUGUST 2017 – REVISED JULY 2018

Changes from Revision A (March 2018) to Revision B	Page
• Changed resistor values in *Typical Arbitrary Waveform Generator Output Drive Circuit* from 49.9 Ω to 40.2 Ω	1
• Changed resistor values in *Typical Arbitrary Waveform Generator Output Drive Circuit* from 24.9 Ω to 30 Ω	1
• Changed "T_A = 25°C" to "T_A ≈ 25°C" in *Electrical Characteristics: ±15 V* condition statement	6
• Changed "100% tested at 25°C" to "100% tested at ≈ 25°C" in the footnote of *Electrical Characteristics: ±15 V*	6
• Added "DDA package only" in Test Conditions column for "V_{OS}" specification	6
• Added new V_{OS} specifiction line for RGT package	6
• Added min/max values to "R_{FB_TRACE}" specification	7
• Changed units from "pF || kΩ" to "kΩ || pF" and changed typical spec accordingly	7
• Added min/max values to "T_{J_SENSE} 25°C value" specification	8
• Changed "T_{J_SENSE} temperature coefficient" specification's typical value from 3 mV/°C to 3.2 mV/°C	8
• Added min/max values to "T_{J_SENSE} input impedance" specification	8
• Changed "T_A = 25°C" to "T_A ≈ 25°C" in *Electrical Characteristics: ±7.5 V* condition statement	9
• Changed "100% tested at 25°C" to "100% tested at ≈ 25°C" in the footnote of *Electrical Characteristics: ±7.5 V*	9
• Added "DDA package only" in Test Conditions column for "V_{OS}" specification	9
• Added new V_{OS} specifiction line for RGT package	9
• Changed units from "pF || kΩ" to "kΩ || pF" and changed typical values accordingly	9
• Added min/max values to "T_{J_SENSE} 25°C value" specification	10
• Added min/max values to "T_{J_SENSE} input impedance" specification	10
• Changed "T_A = 25°C" to "T_A ≈ 25°C" in *Typical Characteristics: ±15 V* condition statement	11
• Changed Z_{OL} low frequency value from 160 dB to 138 dB in *Open-Loop Transimpedance Gain and Phase vs Frequency*	13
• Changed *Overdrive Recovery Time* grid lines and added gain information	14
• Added *T_{J_SENSE} Voltage vs Ambient Temperature*	17
• Changed "T_A = 25°C" to "T_A ≈ 25°C" in *Typical Characteristics: ±7.5 V* condition statement	18
• Changed *Overdrive Recovery Time* grid lines and added gain information	19
• Corrected polarity of negative supply capacitor in *Wideband Noninverting Gain Configuration (5 V/V)*	25
• Corrected negative supply capacitor polarity in *Wideband Inverting Gain Configuration (5 V/V)*	26
• Added "R_{ISO}" to "1 Ω" in *Driving a Large Capacitive Load Using an Output Series Isolation Resistor*	28
• Added 1-kΩ resistor to *Driving a Large Capacitive Load Using an Output Series Isolation Resistor*	28
• Changed supply values from ±15 V to ±7.5 V in *Video Distribution Amplifier Application*	30
• Changed R_{S2} values from 100 Ω to 40.2 Ω in *Load-Sharing Driver Application*	31
• Added 30-Ω resistor to *Load-Sharing Driver Application*	31
• Added text to *Design Requirements* and *Detailed Design Procedure* sections	32
• Added *Application Curves* section	33

The datasheet number will be changing.

Device Family	Change From:	Change To:
THS3491	SBOS875A	SBOS875B

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/THS3491

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

THS3491IDDAR	THS3491IDDAT	THS3491IRGTR	THS3491IRGTT
XTHS3491IRGTR			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com